

**PRESS RELEASE**

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**For Immediate Release**

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## **Solid State Technology published today the column article written by David Lam...**

**Santa Clara, CA - July 11, 2011** - The column summarizes Lam's invited talk on Extending Optical Lithography with CEBL (Complementary E-Beam Lithography), scheduled for Wednesday, July 13, at noon, at the Advanced Lithography TechXPOT.

Solid State Technology publishes today a guest column by David K. Lam, Chairman of Multibeam Corporation. The column summarizes Lam's invited talk on Extending Optical Lithography with CEBL (Complementary E-Beam Lithography), scheduled for Wednesday, July 13, at noon, at the Advanced Lithography TechXPOT.

Lam describes the trend towards 1-D gridded layouts and complementary lithography, as major chip makers seek to reduce costs in high-volume manufacturing (HVM) at advanced technology nodes.

In the guest column, Lam explains that "Complementary lithography draws on the strengths of two lithography technologies, working hand-in-hand, to lower the cost of patterning critical layers in logic devices at 20nm half-pitch and beyond, in HVM." He lays out the key elements that make complementary lithography viable.

In his talk, Lam will further describe Multibeam's implementation of its technology for CEBL applications, including the elimination of the magnetic field to make columns small and fast, and simplifying CEBL column design to enable more robust and manufacturable columns.

"The infrastructure to support complementary lithography exists and is available today," emphasizes Lam. "This eco-system offers a complete solution that scales far beyond the 20nm node."

To read more, visit Solid State Technology at <http://www.electroiq.com/articles/sst/2011/july/extending-optical-lithography-with-complementary-ebeam-lithography.html>.

Lam is scheduled to present on Wednesday, July 13<sup>th</sup> at the Advanced Lithography TechXPOT. Register through Semicon West at <http://semiconwest.org/node/6536>.

### **About Multibeam Corporation**

Headquartered in Santa Clara, California, Multibeam Corporation is a leading developer of multi-column e-beam technologies that add high value to semiconductor lithography by doing away with costly masks. The company's Complementary E-Beam Lithography (CEBL) system augments optical lithography at critical layers by eliminating expensive optical multiple patterning at 20nm processing nodes and beyond. Multibeam's systems can also be cost-efficiently leveraged as primary lithographic tools for low-volume production of ASICs as well as in multi-project wafer programs. Multibeam's patent-protected e-beam technologies encompass deployment of multi-column arrays to perform wafer inspection.

Multibeam is led by Dr. David K. Lam, founder and former CEO of Lam Research Corporation.

For more information, visit [www.multibeamcorp.com](http://www.multibeamcorp.com).